P/N	SH	REV
610-90706-01	1	2.0

NOTES: UNLESS OTHERWISE SPECIFIED

1. SPECIFICATIONS/TOLERANCES:
   A. FABRICATE PER IPC-6012, CLASS 2, USING PROVIDED DATA FILES
   B. ALL SPECIFICATIONS USED SHALL BE PER THEIR LATEST REVISIONS.
   C. THE DIMENSIONS OF CIRCUIT FEATURES IN THE PROVIDED DATA MAY BE ADJUSTED ONLY TO COMPENSATE FOR PROCESS TOLERANCES; ADDING, REMOVING OR RELOCATING CIRCUIT FEATURES, INCLUDING NON-FUNCTIONAL PADS, IS NOT ALLOWED, AND THE DESIGN OF ALL PLANE STRUCTURES MUST BE MAINTAINED TO ENSURE PROPER ELECTRICAL PERFORMANCE.
   D. REMOVE ALL BURRS AND BREAK SHARP EDGES. .381 [.015] MAX RADIUS.
   E. PARENTHETICAL INFORMATION IS FOR REFERENCE ONLY.
   F. REPAIR OF PCB DEFECTS IS NOT PERMITTED.

2. DIELECTRIC MATERIAL:
   A. DIELECTRIC MATERIAL SHALL BE PER IPC-4101/99, /124, /126 OR /129 (RoHS COMPLIANT EPOXY-GLASS).
   B. MINIMUM DIELECTRIC THICKNESS SHALL BE .051 [.002] FOR REFERENCED STACK-UP DIMENSIONS OF.076 [.003] OR GREATER; IPC-6012 REQUIREMENTS SHALL OTHERWISE APPLY. SINGLE-PLY CONSTRUCTION IS ALLOWED.
   C. SEE LAYER STACK-UP FOR REQUIRED COPPER WEIGHTS AND THE FINISHED PCB THICKNESS. IF SPECIFIED, 1/3 OZ. STARTING FOIL MAY BE ACHIEVED BY 1/2 OZ. FOIL REDUCTION.
   D. FINISHED PCB THICKNESS SHALL BE MEASURED OVER LANDS AND/OR CONDUCTORS NOT COVERED BY SOLDER MASK.

3. DRILLING:
   A. VIA DIAMETERS (TOL. = +.051/- DRILL DIAMETER [+.0020/- DRILL DIAMETER]) SHALL BE VERIFIED BEFORE PLATING; ALL OTHER HOLE DIAMETERS SHALL BE VERIFIED AT FINAL INSPECTION.
   B. LAYER-TO-LAYER MISREGISTRATION SHALL BE .127 [.005] MAXIMUM.

4. SOLDER MASK:
   A. APPLY LPI SOLDER MASK USING PROVIDED DATA.
   B. SOLDER MASK SHALL BE PER IPC-SM-840, CLASS T, COLOR BLUE.
   C. THE DIMENSIONS OF SOLDER MASK-DEFINED PADS ON PLANES AND/OR WIDE CONDUCTORS SHALL NOT BE MODIFIED.

5. MARKING:
   A. MARK PCB PER PROVIDED DATA USING SILKSCREEN OR AUTOMATED INJET PROCESSING WITH PERMANENT, NON-CONDUCTIVE INK, COLOR WHITE.
   B. SUPPLIER ID AND TRACEABILITY INFORMATION SHALL BE APPLIED USING PERMANENT, NON-CONDUCTIVE INK, COLOR WHITE.
   C. INK SHALL NOT BE APPLIED TO ANY SOLDERABLE SURFACE.

6. ELECTRICAL TEST:
   A. DESIGN VERIFICATION SHALL BE DONE PRIOR TO PCB FABRICATION USING SUPPLIED VALOR ODB++ DATABASE, OR GERBER DATA AND AN IPC-D-356 NETLIST.
   B. ALL PCBS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS USING PROVIDED DATA.
   C. APPLY TEST STAMP IN NON-LEGEND AREA ON REAR SIDE OF PCB; OK TO APPLY TO PANEL RAILS IF SPACE DOES NOT PERMIT.

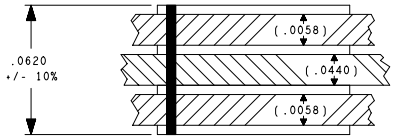
7. FINAL FINISH:
   A. FINAL FINISH ON ALL EXPOSED CONDUCTORS SHALL BE IMMERSION SILVER PER IPC-4553, .15 - .38 MICROMETERS [6 - 15 MICROINCHES] THICK.

8. IMPEDANCE:
   A. IMPEDANCE TOLERANCE SHALL BE +/- 10%.
   B. SEE LAYER STACK-UP FOR IMPEDANCE REQUIREMENTS.

9. IF PANELIZATION SPECIFICATIONS ARE PROVIDED, THE PCBS SHALL BE DELIVERED IN PANEL FORM. HOWEVER, THESE SPECIFICATIONS MAY BE CHANGED AS REQUIRED BY THE CONTRACT MANUFACTURER TO SUPPORT VOLUME ASSEMBLY REQUIREMENTS.

REVISIONS

ECO NO.	REV	DATE	DESCRIPTION	DRAWN	CHECKED	APPROVED
AHUY-21	1.0	03/07/19	INITIAL RELEASE	YJUN	MILI	MILI
MILI104	2.0	07/01/22	UPDATE SILKSCREEN FROM 90658 REV6.0	JYUN	MILI	MILI



LAYER DESCRIPTION	START COPPER WT	SE IMP OHMS	SE TRACE WIDTH	REF LAYER	CPW SPACE	DIFF IMP OHMS	DIFF TRACE WIDTH/SPACE	REF LAYER	CPW SPACE
L01 - TOP	.38 OZ	--	-----	---	-----	90	.00701/.00499	2	-----
L02 - PLANE	1.0 OZ	--	-----	---	-----	---	----	---	-----
L03 - PLANE	1.0 OZ	--	-----	---	-----	---	----	---	-----
L04 - BOTTOM	.38 OZ	--	.-----	---	-----	90	.00701/.00499	3	-----

STACK-UP

SEE BOM	SEE BOM
NEXT ASSY	USED ON
APPLICATION	

THE INFORMATION CONTAINED HEREIN IS CONFIDENTIAL AND PROPRIETARY TO Infineon technologies AG AND SHALL NOT BE REPRODUCED OR DISCLOSED IN WHOLE OR IN PART OR USED FOR ANY DESIGN, MANUFACTURE, OR OTHERWISE, EXCEPT WHEN SUCH USER POSSESSES AUTHORIZATION FROM Infineon

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN METRIC WITH INCHES IN BRACKETS
.XXX ±.064 [±.005] .XX ±.13 [±.01] ANGLES ±.5°

MATERIAL 2

FINISH 7

DO NOT SCALE DRAWING

APPROVALS	DATE
DRAWN JYUN	07/01/22
ENGINEER MILI	07/01/22
CHECKER MILI	07/01/22
QA -	-
PROJ. ENG. -	-

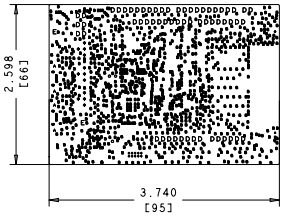
Infineon Technologies AG
IFAG MUC Am Campeon 1-15
85579 NEUBIBERG - GERMANY

TITLE
PCB FABRICATION,
CYW9BTM2BASE2

SIZE	CAGE CODE	P/N
D	-	610-90706-01

SCALE	SHEET	REV
1/1	1 OF 3	2.0

COMPUTER GENERATED DRAWING
DO NOT CHANGE MANUALLY



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	9.84	+1.97/-9.84	PLATED	1196
•	27.56	+2.99/-2.99	PLATED	10
•	31.5	+1.97/-1.97	PLATED	1
•	39.0	+3.0/-3.0	PLATED	3
•	39.0	+3.0/-3.0	PLATED	9
D	39.37	+2.95/-2.95	PLATED	60
°	40.0	+3.0/-3.0	PLATED	3
•	40.16	+3.0/-3.0	PLATED	4
E	51.18	+2.95/-2.95	PLATED	2
	169.29	+2.95/-2.95	PLATED	1
•	31.5	+1.97/-1.97	NON-PLATED	1
	43.31	+1.97/-1.97	NON-PLATED	1
	62.99	+1.97/-1.97	NON-PLATED	1
•	37.4x25.59	+5.0/-5.0	PLATED	4
•	47.24x27.56	+5.0/-5.0	PLATED	4

THE INFORMATION CONTAINED HEREIN IS CONFIDENTIAL AND PROPRIETARY TO Infineon technologies AG AND SHALL NOT BE REPRODUCED OR DISCLOSED IN WHOLE OR IN PART OR USED FOR ANY DESIGN, MANUFACTURE, OR OTHERWISE, EXCEPT WHEN SUCH USER POSSESSES DIRECT, WRITTEN AUTHORIZATION

COMPUTER GENERATED DRAWING
DO NOT CHANGE MANUALLY